

# Certificate

(1)

(2) Number of Certificate: **ZP/C030/24**

(3) Product: **EN25QH32B (2B) up to ASIL B as SEooC**

(4) Company: **ELITE SEMICONDUCTOR MICROELECTRONICS TECHNOLOGY INC.**

(5) Address: **No.23 Industrial East Fourth Road, Science Park, Hsinchu City, Taiwan**

(6) The design and construction of this products and any acceptable variation thereto are specified in the schedule to this certificate.

(7) The certification body of DEKRA Testing and Certification GmbH certifies that these products have been found to comply with the requirements pursuant to the standard(s) referred in section 8. The examination and test results are recorded in the test and assessment report FSAR\_15012024A\_V1\_ESMT.

(8) The requirements are assured by compliance with the following standard(s):

**ISO 26262-2:2018 ISO 26262-5:2018 ISO 26262-8:2018 ISO 26262-11:2018**

(9) This certificate only relates to the design, examination and tests of the specified products in accordance with the mentioned standard(s). Further requirements apply to the manufacturing process and supply of this equipment. These are not covered by this certificate.

(10) This certificate is valid until 2029-05-19

DEKRA Testing and Certification GmbH  
Bochum, 2024-05-20



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Managing Director

- (11) Appendix to
- (12) **Certificate**  
**ZP/C030/24**
- (13) 13.1 Subject and Type:  
EN25QH32B (2B)

### 13.2 Description

The EN25QH32B (2B) **Integrated Circuit - IC** provides simultaneous programming of 1 to 256 bytes using the Page Program instruction, as well as single-sector/block or full-chip erase capability. This provides granular control over data processing and storage, which is critical for safety-critical applications. The ECC self-tests described in the Safety Manual, which can be programmed into the application during the initialisation and continuous operation phases, can detect random errors within the defined FTTI. Another important feature of the EN25QH32B (2B) **Integrated Circuit - IC** is its proven reliability. Through extensive use in a variety of applications and environments, the IC has demonstrated its robustness and reliability. This is a critical feature for demonstrating system integrity and for certification in safety-critical environments.

Safety Goal of the EN25QH32B (2B) is listed below

<b>Hazard</b>	Safety critical graphic images displayed not correctly
<b>Safety Goal</b>	When safety critical graphic images are displayed by LCD, they shall be displayed correctly.
<b>ASIL</b>	B
<b>Safe State</b>	Black Screen or Display warning messages
<b>FTTI</b>	1 Second

- (14) Assessment Report(s)  
FSAR\_15012024A\_V1\_ESMT dd. 2024-05-14
- (15) Special Conditions for Safe Use  
The Memory IC listed under (3) can be used for applications up to ASIL B as a **Safety Element out of Context - SEooC** in compliance with the conditions described in the 210-332B (LB)-018\_1 0 Safety manual for the EN25QH32B (2B). The safety manual also describes several assumptions-of-use and give a guideline of possible decompositions with external elements.